

**Amendments to the Claims**

Claims 1-3 (*Cancelled*)

4. *(Currently Amended)* ~~A carrier with a first and a second side, comprising a stack of:~~

~~— a first etch mask;~~  
~~— a first metal layer;~~  
~~— an intermediate layer;~~  
~~— a second metal layer and~~  
~~— a second etch mask,~~  
~~— the first etch mask being situated on the first side of the carrier, and the second etch mask being situated on the second side of the carrier.~~

An electronic device comprising a carrier having, between a first side and an opposite second side,

    a first etch mask,  
    a first patterned metal layer,  
    a patterned intermediate layer,  
    a second patterned metal layer and  
    a second etch mask for use of etching of the second metal layer,  
    wherein the first and second etch mask each have an adhesive layer for solder,  
    wherein the first patterned metal layer is electroconductively connected to an electric element and to the second metal layer, and the first patterned metal layer further includes parts projecting with respect to the intermediate layer, the projecting parts of the first metal layer are anchored in the envelope which electric element is present on the first side of the carrier,

    wherein contacts of the electric element are electroconductively connected to the first metal layer, and

    wherein the electronic device includes a first and a second electric element, the electric elements are interconnected by an interconnect track that is defined

in the first metal layer, while a corresponding interconnect track is absent in the second metal layer.

5. (*Cancelled*)

6. (*Currently Amended*) A carrier as claimed in claim 4, characterized in that The electronic device as recited in claim 4, wherein the first and the second etch mask comprise an adhesive layer for solder.

7. (*Currently Amended*) A carrier as claimed in claim 6, characterized in that The electronic device as recited in claim 6, wherein the adhesive layer for solder comprises a material selected from the group composed of Ag, NiPd, NiPdAu.

8. (*Currently Amended*) A carrier as claimed in claim 4, characterized in that The electronic device as recited in claim 4, wherein the intermediate layer comprises an electroconductive material that can suitably be used as a solder stop.

9. (*Currently Amended*) A carrier as claimed in claim 8, characterized in that The electronic device as recited in claim 8, wherein the intermediate layer comprises a material selected from the group composed of Al, an alloy of Al, FeNi, FeCrNi and stainless steel, and that the first and the third metal layer the first patterned metal layer and the second patterned metal layer contain copper.

Claims 10-12 (*Cancelled*)

13. (*New*) The electronic device as recited in claim 4, wherein the intermediate layer is made from a material that can be selectively etched with respect to the first patterned metal layer.

14. (*New*) The electronic device as recited in claim 13, wherein the intermediate layer is a metal.

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15. (*New*) The electronic device as recited in claim 14, wherein the intermediate layer comprises a material selected from the group composed of Al, an alloy of Al, FeNi, FeCrNi and stainless steel, and that the first patterned metal layer and the second patterned metal layer contain copper.
16. (*New*) The electronic device as recited in claim 4, wherein the first electric element is a semiconductor element which is placed on the first side of the carrier with a flip-chip technique.
17. (*New*) The electronic device as recited in claim 16, wherein connection conductors are defined in the second patterned metal layer and the corresponding etch mask, said connection conductors are laterally displaced with respect to contacts in the semiconductor element.